



# TaiSol Group

2017

**Investor Conference** 

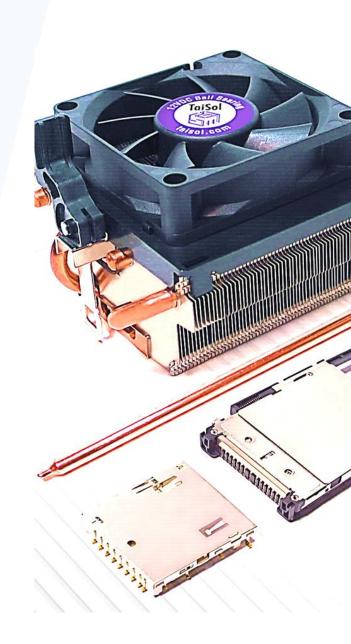
Spokesperson:郭尚仁



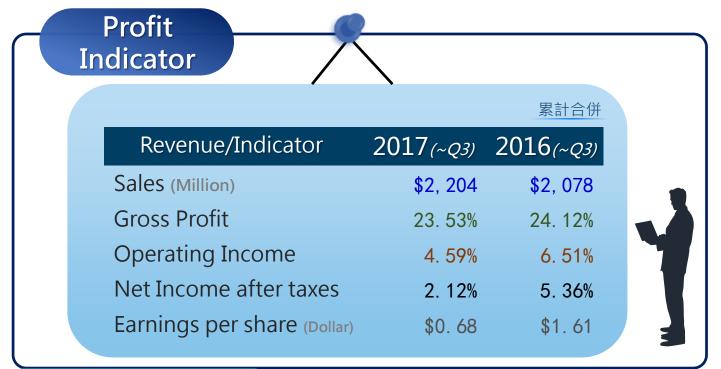
#### **2017** (~Q3) Performance

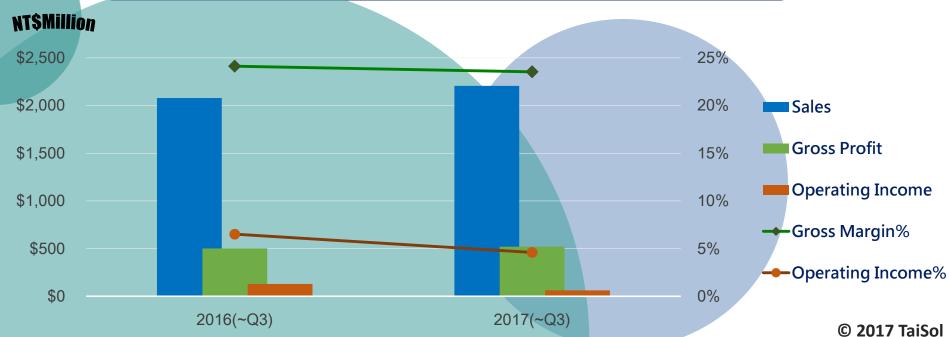
2015 ~2017 Growing

**3** 2018 Prospect









### Sales Proportion

2017 Q1-Q3



**Consumer Electronics** 



Thermal Module Heat pipe

73%



Connector · I/O

22%



C/R · Mobile Pay

3%



New Market New Appliance

2%

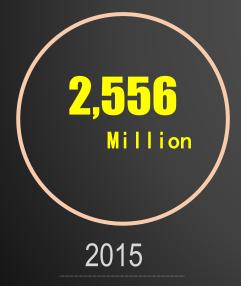
Revenue



## Annual Sales

2015,2016, 2017~Oct.













Drives of Business Performance

#### ------Apply & Integrate-----



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### Product Strategy & Drivers of Growth

**Server Continuous** 

Extension of Telecommunication

Creating New Energy

Application

















**Drives of Growth** 







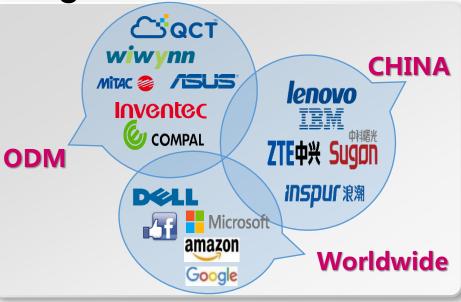
#### **56** Mobile Telecommunication



#### Server/Clouding Computing

**Heat Dispassion Solutions** 







Full CPU Platform









# New Energy Transportation Thermal Expansion Solution



















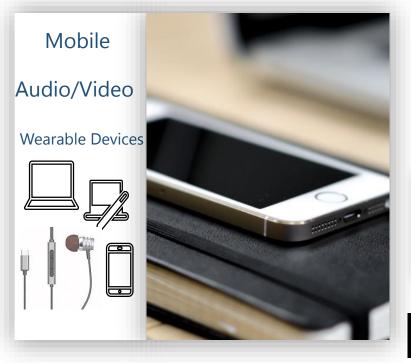






#### Smartphone / High-performance Devices







- ✓ Rated at up to 100W
- ✓ Power Delivery Capacity to 5A (100W) Max.
- ✓ Gen1 (5Gbps) / Gen2 (10Gbps)
- ✓ Reversible to prevent the Damage while connecting

High-End 24 pin Water-Proof







- Full Product Series (IPX Class)
- Automation Manufacturing
- USB-IF TID Certification

Mid-End 24 pin Standard





# 2018 Prospect —











18%



9%

PC

**Telecom/Server** 

**Consumer Electronics** 

New Energy Appliances



